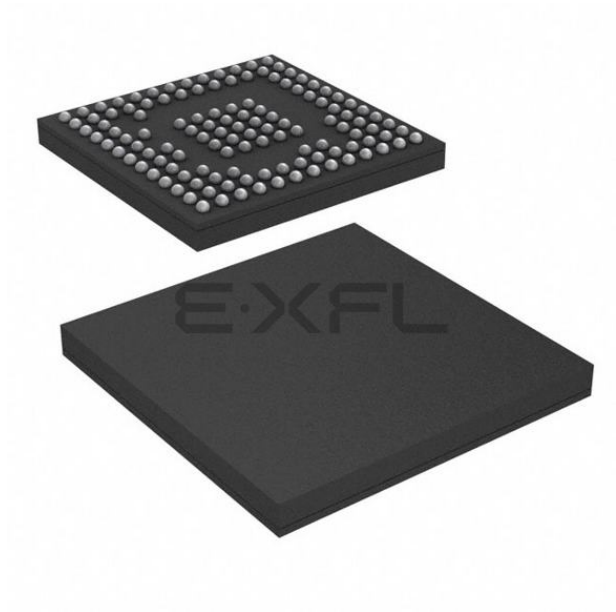

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	65
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D - 12b SAR
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TJ)
Mounting Type	Surface Mount
Package / Case	125-VFBGA
Supplier Device Package	125-BGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32jg12b500f1024il125-c

4. Electrical Specifications

4.1 Electrical Characteristics

All electrical parameters in all tables are specified under the following conditions, unless stated otherwise:

- Typical values are based on T_{AMB}=25 °C and V_{DD}= 3.3 V, by production test and/or technology characterization.
- Minimum and maximum values represent the worst conditions across supply voltage, process variation, and operating temperature, unless stated otherwise.

Refer to 4.1.2.1 General Operating Conditions for more details about operational supply and temperature limits.

4.1.1 Absolute Maximum Ratings

Stresses above those listed below may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability. For more information on the available quality and reliability data, see the Quality and Reliability Monitor Report at http://www.silabs.com/support/quality/pages/default.aspx.

Table 4.1. Absolute Maximum Ratings

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Storage temperature range	T_{STG}		-50	—	150	°C
Voltage on any supply pin	V_{DDMAX}		-0.3	—	3.8	V
Voltage ramp rate on any supply pin	$V_{DDRAMPMAX}$		—	—	1	V / µs
DC voltage on any GPIO pin	V_{DIGPIN}	5V tolerant GPIO pins[1]	-0.3	—	Min of 5.25 and IOVDD +2	V
		Non-5V tolerant GPIO pins	-0.3	—	IOVDD+0.3	V
Voltage on HFXO pins	$V_{HFXOPIN}$		-0.3	—	1.4	V
Total current into VDD power lines	I_{VDDMAX}	Source	—	—	200	mA
Total current into VSS ground lines	I_{VSSMAX}	Sink	—	—	200	mA
		Sink	—	—	200	mA
Current per I/O pin	I_{IOMAX}	Sink	—	—	50	mA
		Source	—	—	50	mA
Current for all I/O pins	$I_{IOALLMAX}$	Sink	—	—	200	mA
		Source	—	—	200	mA
Junction temperature	T_J	-G grade devices	-40	—	105	°C
		-I grade devices	-40	—	125	°C

Note:

1. When a GPIO pin is routed to the analog module through the APORT, the maximum voltage = IOVDD.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in EM4S mode	I_{EM4S}	No RAM retention, no RTCC	—	0.07	TBD	µA

Note:

1. CMU_HFXOCTRL_LOWPOWER=1.
2. CMU_LFRCOCTRL_ENVREF = 1, CMU_LFRCOCTRL_VREFUPDATE = 1

4.1.7 Brown Out Detector (BOD)

Table 4.9. Brown Out Detector (BOD)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
DVDD BOD threshold	$V_{DVDDBOD}$	DVDD rising	—	—	TBD	V
		DVDD falling (EM0/EM1)	TBD	—	—	V
		DVDD falling (EM2/EM3)	TBD	—	—	V
DVDD BOD hysteresis	$V_{DVDDBOD\_HYST}$		—	18	—	mV
DVDD BOD response time	$t_{DVDDBOD\_DELAY}$	Supply drops at 0.1V/µs rate	—	2.4	—	µs
AVDD BOD threshold	$V_{AVDDBOD}$	AVDD rising	—	—	TBD	V
		AVDD falling (EM0/EM1)	TBD	—	—	V
		AVDD falling (EM2/EM3)	TBD	—	—	V
AVDD BOD hysteresis	$V_{AVDDBOD\_HYST}$		—	20	—	mV
AVDD BOD response time	$t_{AVDDBOD\_DELAY}$	Supply drops at 0.1V/µs rate	—	2.4	—	µs
EM4 BOD threshold	$V_{EM4DBOD}$	AVDD rising	—	—	TBD	V
		AVDD falling	TBD	—	—	V
EM4 BOD hysteresis	V_{EM4BOD_HYST}		—	25	—	mV
EM4 BOD response time	t_{EM4BOD_DELAY}	Supply drops at 0.1V/µs rate	—	300	—	µs

4.1.9 Flash Memory Characteristics[3]

Table 4.16. Flash Memory Characteristics[3]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Flash erase cycles before failure	EC_{FLASH}		10000	—	—	cycles
Flash data retention	RET_{FLASH}	T_{AMB} ≤ 85 °C	10	—	—	years
		T_{AMB} ≤ 125 °C	10	—	—	years
Word (32-bit) programming time	t_{W_PROG}		20	24.4	30	µs
Page erase time	t_{PERASE}		20	26.4	35	ms
Mass erase time[1]	t_{MERASE}		20	26.5	35	ms
Device erase time[2]	t_{DERASE}	T_{AMB} ≤ 85 °C	—	69	100	ms
		T_{AMB} ≤ 125 °C	—	69	110	ms
Page erase current[4]	I_{ERASE}		—	—	1.6	mA
Write current[4]	I_{WRITE}		—	—	3.8	mA
Supply voltage during flash erase and write	V_{FLASH}		1.62	—	TBD	V

Note:

1. Mass erase is issued by the CPU and erases all flash.
2. Device erase is issued over the AAP interface and erases all flash, SRAM, the Lock Bit (LB) page, and the User data page Lock Word (ULW).
3. Flash data retention information is published in the Quarterly Quality and Reliability Report.
4. Measured at 25 °C.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
ADC clock frequency	f_{ADCCLK}		—	—	16	MHz
Throughput rate	$f_{ADCRATE}$		—	—	1	Msps
Conversion time[1]	$t_{ADCCONV}$	6 bit	—	7	—	cycles
		8 bit	—	9	—	cycles
		12 bit	—	13	—	cycles
Startup time of reference generator and ADC core	$t_{ADCSTART}$	WARMUPMODE[4] = NORMAL	—	—	5	µs
		WARMUPMODE[4] = KEEPIN-STANDBY	—	—	2	µs
		WARMUPMODE[4] = KEEPINSLO-WACC	—	—	1	µs
SNDR at 1Msps and f_{IN} = 10kHz	$SNDR_{ADC}$	Internal reference, 2.5 V full-scale, differential (-1.25, 1.25)	TBD	67	—	dB
		vrefp_in = 1.25 V direct mode with 2.5 V full-scale, differential	—	68	—	dB
Spurious-free dynamic range (SFDR)	$SFDR_{ADC}$	1 MSamples/s, 10 kHz full-scale sine wave	—	75	—	dB
Differential non-linearity (DNL)	DNL_{ADC}	12 bit resolution, No missing co-des	TBD	—	TBD	LSB
Integral non-linearity (INL), End point method	INL_{ADC}	12 bit resolution	TBD	—	TBD	LSB
Offset error	$V_{ADCOFFSETERR}$		TBD	0	TBD	LSB
Gain error in ADC	$V_{ADCGAIN}$	Using internal reference	—	-0.2	TBD	%
		Using external reference	—	-1	—	%
Temperature sensor slope	V_{TS_SLOPE}		—	-1.84	—	mV/°C

Note:

1. Derived from ADCCLK.
2. PSRR is referenced to AVDD when ANASW=0 and to DVDD when ANASW=1 in EMU_PWRCTRL.
3. In ADCn_BIASPROG register.
4. In ADCn_CNTL register.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Settling time, (output settled within 1% of steady state value),	t_{IDAC_SETTLE}	Range setting is changed	—	5	—	µs
		Step value is changed	—	1	—	µs
Current consumption[2]	I_{IDAC}	EM0 or EM1 Source mode, excluding output current	—	8.9	TBD	µA
		EM0 or EM1 Sink mode, excluding output current	—	12	TBD	µA
		EM2 or EM3 Source mode, excluding output current, T = 25 °C	—	1.04	—	µA
		EM2 or EM3 Sink mode, excluding output current, T = 25 °C	—	1.08	—	µA
		EM2 or EM3 Source mode, excluding output current, T ≥ 85 °C	—	8.9	—	µA
		EM2 or EM3 Sink mode, excluding output current, T ≥ 85 °C	—	12	—	µA
Output voltage compliance in source mode, source current change relative to current sourced at 0 V	I_{COMP_SRC}	RANGESEL1=0, output voltage = min(V_{IOVDD}, V_{AVDD}[2]-100 mv)	—	0.11	—	%
		RANGESEL1=1, output voltage = min(V_{IOVDD}, V_{AVDD}[2]-100 mV)	—	0.06	—	%
		RANGESEL1=2, output voltage = min(V_{IOVDD}, V_{AVDD}[2]-150 mV)	—	0.04	—	%
		RANGESEL1=3, output voltage = min(V_{IOVDD}, V_{AVDD}[2]-250 mV)	—	0.03	—	%
Output voltage compliance in sink mode, sink current change relative to current sunk at IOVDD	I_{COMP_SINK}	RANGESEL1=0, output voltage = 100 mV	—	0.12	—	%
		RANGESEL1=1, output voltage = 100 mV	—	0.05	—	%
		RANGESEL1=2, output voltage = 150 mV	—	0.04	—	%
		RANGESEL1=3, output voltage = 250 mV	—	0.03	—	%

Note:

1. In IDAC_CURPROG register.
2. The IDAC is supplied by either AVDD, DVDD, or IOVDD based on the setting of ANASW in the EMU_PWRCTRL register and PWRSEL in the IDAC_CTRL register. Setting PWRSEL to 1 selects IOVDD. With PWRSEL cleared to 0, ANASW selects between AVDD (0) and DVDD (1).

4.1.17 Operational Amplifier (OPAMP)

Unless otherwise indicated, specified conditions are: Non-inverting input configuration, VDD = 3.3 V, DRIVESTRENGTH = 2, MAINOUTEN = 1, C_{LOAD} = 75 pF with OUTSCALE = 0, or C_{LOAD} = 37.5 pF with OUTSCALE = 1. Unit gain buffer and 3X-gain connection as specified in table footnotes[8] [1].

Table 4.24. Operational Amplifier (OPAMP)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supply voltage	V_{OPA}	HCMDIS = 0, Rail-to-rail input range	2	—	3.8	V
		HCMDIS = 1	1.62	—	3.8	V
Input voltage	V_{IN}	HCMDIS = 0, Rail-to-rail input range	V_{VSS}	—	V_{OPA}	V
		HCMDIS = 1	V_{VSS}	—	V_{OPA}-1.2	V
Input impedance	R_{IN}		100	—	—	MΩ
Output voltage	V_{OUT}		V_{VSS}	—	V_{OPA}	V
Load capacitance[2]	C_{LOAD}	OUTSCALE = 0	—	—	75	pF
		OUTSCALE = 1	—	—	37.5	pF
Output impedance	R_{OUT}	DRIVESTRENGTH = 2 or 3, 0.4 V ≤ V_{OUT} ≤ V_{OPA} - 0.4 V, -8 mA < I_{OUT} < 8 mA, Buffer connection, Full supply range	—	0.25	—	Ω
		DRIVESTRENGTH = 0 or 1, 0.4 V ≤ V_{OUT} ≤ V_{OPA} - 0.4 V, -400 µA < I_{OUT} < 400 µA, Buffer connection, Full supply range	—	0.6	—	Ω
		DRIVESTRENGTH = 2 or 3, 0.1 V ≤ V_{OUT} ≤ V_{OPA} - 0.1 V, -2 mA < I_{OUT} < 2 mA, Buffer connection, Full supply range	—	0.4	—	Ω
		DRIVESTRENGTH = 0 or 1, 0.1 V ≤ V_{OUT} ≤ V_{OPA} - 0.1 V, -100 µA < I_{OUT} < 100 µA, Buffer connection, Full supply range	—	1	—	Ω
Internal closed-loop gain	G_{CL}	Buffer connection	TBD	1	TBD	-
		3x Gain connection	TBD	2.99	TBD	-
		16x Gain connection	TBD	15.7	TBD	-
Active current[4]	I_{OPA}	DRIVESTRENGTH = 3, OUTSCALE = 0	—	580	—	µA
		DRIVESTRENGTH = 2, OUTSCALE = 0	—	176	—	µA
		DRIVESTRENGTH = 1, OUTSCALE = 0	—	13	—	µA
		DRIVESTRENGTH = 0, OUTSCALE = 0	—	4.7	—	µA

4.1.20.3 I2C Fast-mode Plus (Fm+)[1]

Table 4.29. I2C Fast-mode Plus (Fm+)[1]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCL clock frequency[2]	f_{SCL}		0	—	1000	kHz
SCL clock low time	t_{LOW}		0.5	—	—	µs
SCL clock high time	t_{HIGH}		0.26	—	—	µs
SDA set-up time	t_{SU_DAT}		50	—	—	ns
SDA hold time	t_{HD_DAT}		100	—	—	ns
Repeated START condition set-up time	t_{SU_STA}		0.26	—	—	µs
(Repeated) START condition hold time	t_{HD_STA}		0.26	—	—	µs
STOP condition set-up time	t_{SU_STO}		0.26	—	—	µs
Bus free time between a STOP and START condition	t_{BUF}		0.5	—	—	µs

Note:
1. For CLHR set to 0 or 1 in the I2Cn_CTRL register.
2. For the minimum HFPERCLK frequency required in Fast-mode Plus, refer to the I2C chapter in the reference manual.

6. Pin Definitions

6.1 EFM32JG12B5xx in BGA125 Device Pinout

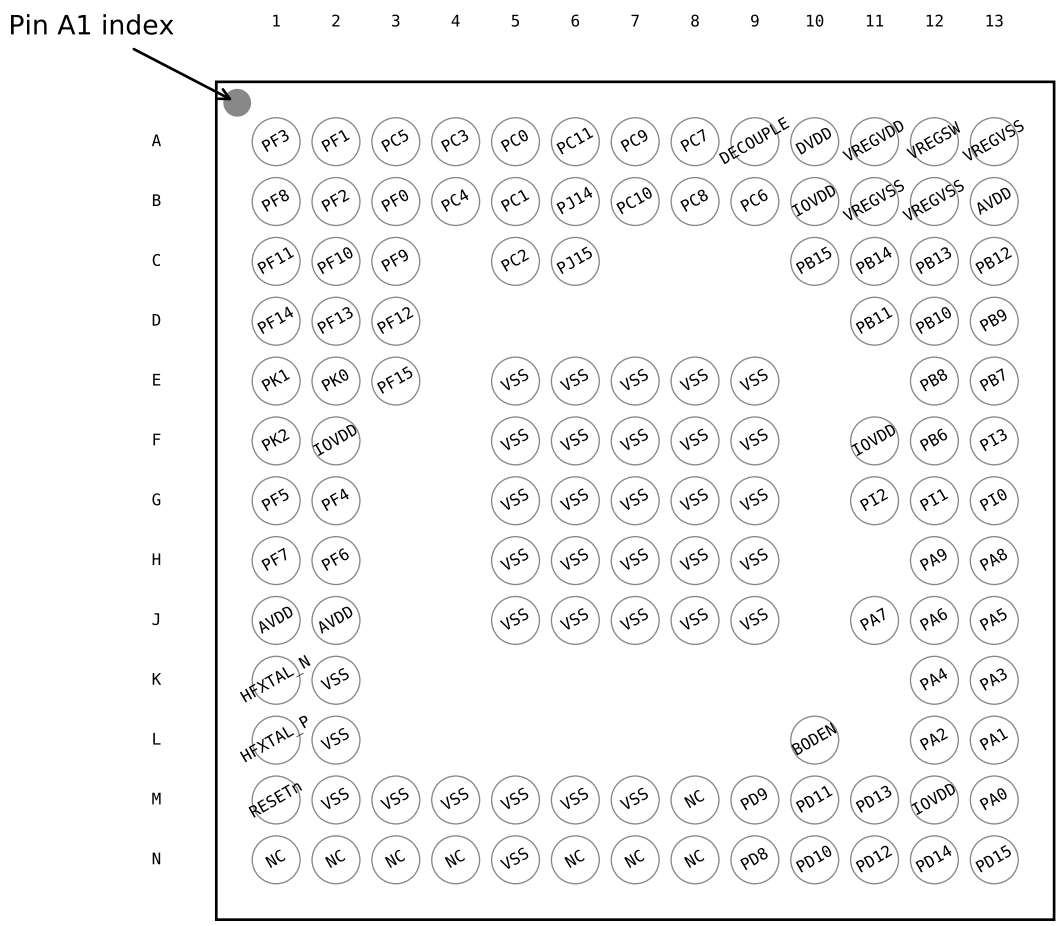

Figure 6.1. EFM32JG12B5xx in BGA125 Device Pinout

Pin		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
B8	PC8	BUSBY BUSAX	TIM0_CC0 #13 TIM0_CC1 #12 TIM0_CC2 #11 TIM0_CDTI0 #10 TIM0_CDTI1 #9 TIM0_CDTI2 #8 TIM1_CC0 #13 TIM1_CC1 #12 TIM1_CC2 #11 TIM1_CC3 #10 WTIM0_CC0 #28 WTIM0_CC1 #26 WTIM0_CC2 #24 WTIM0_CDTI0 #20 WTIM0_CDTI1 #18 WTIM0_CDTI2 #16 WTIM1_CC0 #12 WTIM1_CC1 #10 WTIM1_CC2 #8 WTIM1_CC3 #6 LE-TIM0_OUT0 #13 LE-TIM0_OUT1 #12 PCNT0_S0IN #13 PCNT0_S1IN #12	US0_TX #13 US0_RX #12 US0_CLK #11 US0_CS #10 US0_CTS #9 US0_RTS #8 US1_TX #13 US1_RX #12 US1_CLK #11 US1_CS #10 US1_CTS #9 US1_RTS #8 LEU0_TX #13 LEU0_RX #12 I2C0_SDA #13 I2C0_SCL #12	PRS_CH0 #10 PRS_CH9 #13 PRS_CH10 #2 PRS_CH11 #1 ACMP0_O #13 ACMP1_O #13 ETM_TD1 #3
B9	PC6	BUSBY BUSAX	TIM0_CC0 #11 TIM0_CC1 #10 TIM0_CC2 #9 TIM0_CDTI0 #8 TIM0_CDTI1 #7 TIM0_CDTI2 #6 TIM1_CC0 #11 TIM1_CC1 #10 TIM1_CC2 #9 TIM1_CC3 #8 WTIM0_CC0 #26 WTIM0_CC1 #24 WTIM0_CC2 #22 WTIM0_CDTI0 #18 WTIM0_CDTI1 #16 WTIM0_CDTI2 #14 WTIM1_CC0 #10 WTIM1_CC1 #8 WTIM1_CC2 #6 WTIM1_CC3 #4 LE-TIM0_OUT0 #11 LE-TIM0_OUT1 #10 PCNT0_S0IN #11 PCNT0_S1IN #10	US0_TX #11 US0_RX #10 US0_CLK #9 US0_CS #8 US0_CTS #7 US0_RTS #6 US1_TX #11 US1_RX #10 US1_CLK #9 US1_CS #8 US1_CTS #7 US1_RTS #6 LEU0_TX #11 LEU0_RX #10 I2C0_SDA #11 I2C0_SCL #10	CMU_CLK0 #2 CMU_CLKI0 #2 PRS_CH0 #8 PRS_CH9 #11 PRS_CH10 #0 PRS_CH11 #5 ACMP0_O #11 ACMP1_O #11 ETM_TCLK #3
B10	IOVDD	Digital IO power supply .			
B11	VREGVSS	Voltage regulator VSS			
B12	VREGVSS	Voltage regulator VSS			
B13	AVDD	Analog power supply .			

Pin		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
C1	PF11	BUSAY BUSBX	WTIM1_CC2 #31 WTIM1_CC3 #29 PCNT1_S0IN #24 PCNT1_S1IN #23 PCNT2_S0IN #24 PCNT2_S1IN #23	US2_TX #24 US2_RX #23 US2_CLK #22 US2_CS #21 US2_CTS #20 US2_RTS #19 US3_TX #24 US3_RX #23 US3_CLK #22 US3_CS #21 US3_CTS #20 US3_RTS #19 I2C1_SDA #24 I2C1_SCL #23	ETM_TD2 #0
C2	PF10	BUSBY BUSAX	WTIM1_CC2 #30 WTIM1_CC3 #28 PCNT1_S0IN #23 PCNT1_S1IN #22 PCNT2_S0IN #23 PCNT2_S1IN #22	US2_TX #23 US2_RX #22 US2_CLK #21 US2_CS #20 US2_CTS #19 US2_RTS #18 I2C1_SDA #23 I2C1_SCL #22	ETM_TD1 #0
C3	PF9	BUSAY BUSBX	WTIM1_CC1 #31 WTIM1_CC2 #29 WTIM1_CC3 #27 PCNT1_S0IN #22 PCNT1_S1IN #21 PCNT2_S0IN #22 PCNT2_S1IN #21	US2_TX #22 US2_RX #21 US2_CLK #20 US2_CS #19 US2_CTS #18 US2_RTS #17 I2C1_SDA #22 I2C1_SCL #21	ETM_TD0 #0
C5	PC2	BUSBY BUSAX	WTIM0_CC0 #22 WTIM0_CC1 #20 WTIM0_CC2 #18 WTIM0_CDTI0 #14 WTIM0_CDTI1 #12 WTIM0_CDTI2 #10 WTIM1_CC0 #6 WTIM1_CC1 #4 WTIM1_CC2 #2 WTIM1_CC3 #0 PCNT1_S0IN #15 PCNT1_S1IN #14 PCNT2_S0IN #15 PCNT2_S1IN #14	US3_TX #20 US3_RX #19 US3_CLK #18 US3_CS #17 US3_CTS #16 US3_RTS #15 I2C1_SDA #15 I2C1_SCL #14	
C6	PJ15	BUSACMP1Y BUSACMP1X	PCNT1_S0IN #12 PCNT1_S1IN #11 PCNT2_S0IN #12 PCNT2_S1IN #11	US3_TX #17 US3_RX #16 US3_CLK #15 US3_CS #14 US3_CTS #13 US3_RTS #12 I2C1_SDA #12 I2C1_SCL #11	LES_ALTEX3

Pin		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
H12	PA9	BUSACMP0Y BUSACMP0X	WTIM0_CC0 #9 WTIM0_CC1 #7 WTIM0_CC2 #5 WTIM0_CDTI0 #1 PCNT1_S0IN #3 PCNT1_S1IN #2 PCNT2_S0IN #3 PCNT2_S1IN #2	US2_TX #4 US2_RX #3 US2_CLK #2 US2_CS #1 US2_CTS #0 US2_RTS #31 I2C1_SDA #3 I2C1_SCL #2	LES_ALTEX1 ETM_TD3 #1
H13	PA8	BUSACMP0Y BUSACMP0X	WTIM0_CC0 #8 WTIM0_CC1 #6 WTIM0_CC2 #4 WTIM0_CDTI0 #0 PCNT1_S0IN #2 PCNT1_S1IN #1 PCNT2_S0IN #2 PCNT2_S1IN #1	US2_TX #3 US2_RX #2 US2_CLK #1 US2_CS #0 US2_CTS #31 US2_RTS #30 I2C1_SDA #2 I2C1_SCL #1	LES_ALTEX0 ETM_TD2 #1
J1	AVDD	Analog power supply .			
J2	AVDD	Analog power supply .			
J5	VSS	Ground			
J6	VSS	Ground			
J7	VSS	Ground			
J8	VSS	Ground			
J9	VSS	Ground			
J11	PA7	BUSCY BUSDX	WTIM0_CC0 #7 WTIM0_CC1 #5 WTIM0_CC2 #3 PCNT1_S0IN #1 PCNT1_S1IN #0 PCNT2_S0IN #1 PCNT2_S1IN #0	US2_TX #2 US2_RX #1 US2_CLK #0 US2_CS #31 US2_CTS #30 US2_RTS #29 I2C1_SDA #1 I2C1_SCL #0	LES_CH15 ETM_TD1 #1
J12	PA6	BUSDY BUSCX	WTIM0_CC0 #6 WTIM0_CC1 #4 WTIM0_CC2 #2 PCNT1_S0IN #0 PCNT1_S1IN #31 PCNT2_S0IN #0 PCNT2_S1IN #31	US2_TX #1 US2_RX #0 US2_CLK #31 US2_CS #30 US2_CTS #29 US2_RTS #28 I2C1_SDA #0 I2C1_SCL #31	LES_CH14 ETM_TD0 #1

Table 6.3. EFM32JG12B5xx in QFN48 Device Pinout

Pin		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
0	VSS	Ground			
1	PF0	BUSBY BUSAX	TIM0_CC0 #24 TIM0_CC1 #23 TIM0_CC2 #22 TIM0_CDTI0 #21 TIM0_CDTI1 #20 TIM0_CDTI2 #19 TIM1_CC0 #24 TIM1_CC1 #23 TIM1_CC2 #22 TIM1_CC3 #21 WTIM0_CDTI1 #30 WTIM0_CDTI2 #28 WTIM1_CC0 #24 WTIM1_CC1 #22 WTIM1_CC2 #20 WTIM1_CC3 #18 LE-TIM0_OUT0 #24 LE-TIM0_OUT1 #23 PCNT0_S0IN #24 PCNT0_S1IN #23	US0_TX #24 US0_RX #23 US0_CLK #22 US0_CS #21 US0_CTS #20 US0_RTS #19 US1_TX #24 US1_RX #23 US1_CLK #22 US1_CS #21 US1_CTS #20 US1_RTS #19 US2_TX #14 US2_RX #13 US2_CLK #12 US2_CS #11 US2_CTS #10 US2_RTS #9 LEU0_TX #24 LEU0_RX #23 I2C0_SDA #24 I2C0_SCL #23	PRS_CH0 #0 PRS_CH1 #7 PRS_CH2 #6 PRS_CH3 #5 ACMP0_O #24 ACMP1_O #24 DBG_SWCLKTCK BOOT_TX
2	PF1	BUSAY BUSBX	TIM0_CC0 #25 TIM0_CC1 #24 TIM0_CC2 #23 TIM0_CDTI0 #22 TIM0_CDTI1 #21 TIM0_CDTI2 #20 TIM1_CC0 #25 TIM1_CC1 #24 TIM1_CC2 #23 TIM1_CC3 #22 WTIM0_CDTI1 #31 WTIM0_CDTI2 #29 WTIM1_CC0 #25 WTIM1_CC1 #23 WTIM1_CC2 #21 WTIM1_CC3 #19 LE-TIM0_OUT0 #25 LE-TIM0_OUT1 #24 PCNT0_S0IN #25 PCNT0_S1IN #24	US0_TX #25 US0_RX #24 US0_CLK #23 US0_CS #22 US0_CTS #21 US0_RTS #20 US1_TX #25 US1_RX #24 US1_CLK #23 US1_CS #22 US1_CTS #21 US1_RTS #20 US2_TX #15 US2_RX #14 US2_CLK #13 US2_CS #12 US2_CTS #11 US2_RTS #10 LEU0_TX #25 LEU0_RX #24 I2C0_SDA #25 I2C0_SCL #24	PRS_CH0 #1 PRS_CH1 #0 PRS_CH2 #7 PRS_CH3 #6 ACMP0_O #25 ACMP1_O #25 DBG_SWDIOTMS BOOT_RX

Pin		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
26	PA1	BUSCY BUSDX ADC0_EXTP VDAC0_EXT	TIM0_CC0 #1 TIM0_CC1 #0 TIM0_CC2 #31 TIM0_CDTI0 #30 TIM0_CDTI1 #29 TIM0_CDTI2 #28 TIM1_CC0 #1 TIM1_CC1 #0 TIM1_CC2 #31 TIM1_CC3 #30 WTIM0_CC0 #1 LE-TIM0_OUT0 #1 LE-TIM0_OUT1 #0 PCNT0_S0IN #1 PCNT0_S1IN #0	US0_TX #1 US0_RX #0 US0_CLK #31 US0_CS #30 US0_CTS #29 US0_RTS #28 US1_TX #1 US1_RX #0 US1_CLK #31 US1_CS #30 US1_CTS #29 US1_RTS #28 LEU0_TX #1 LEU0_RX #0 I2C0_SDA #1 I2C0_SCL #0	CMU_CLK0 #0 PRS_CH6 #1 PRS_CH7 #0 PRS_CH8 #10 PRS_CH9 #9 ACMP0_O #1 ACMP1_O #1 LES_CH9
27	PA2	VDAC0_OUT1ALT / OPA1_OUTALT #1 BUSDY BUSCX OPA0_P	TIM0_CC0 #2 TIM0_CC1 #1 TIM0_CC2 #0 TIM0_CDTI0 #31 TIM0_CDTI1 #30 TIM0_CDTI2 #29 TIM1_CC0 #2 TIM1_CC1 #1 TIM1_CC2 #0 TIM1_CC3 #31 WTIM0_CC0 #2 WTIM0_CC1 #0 LE-TIM0_OUT0 #2 LE-TIM0_OUT1 #1 PCNT0_S0IN #2 PCNT0_S1IN #1	US0_TX #2 US0_RX #1 US0_CLK #0 US0_CS #31 US0_CTS #30 US0_RTS #29 US1_TX #2 US1_RX #1 US1_CLK #0 US1_CS #31 US1_CTS #30 US1_RTS #29 LEU0_TX #2 LEU0_RX #1 I2C0_SDA #2 I2C0_SCL #1	PRS_CH6 #2 PRS_CH7 #1 PRS_CH8 #0 PRS_CH9 #10 ACMP0_O #2 ACMP1_O #2 LES_CH10
28	PA3	BUSCY BUSDX VDAC0_OUT0 / OPA0_OUT	TIM0_CC0 #3 TIM0_CC1 #2 TIM0_CC2 #1 TIM0_CDTI0 #0 TIM0_CDTI1 #31 TIM0_CDTI2 #30 TIM1_CC0 #3 TIM1_CC1 #2 TIM1_CC2 #1 TIM1_CC3 #0 WTIM0_CC0 #3 WTIM0_CC1 #1 LE-TIM0_OUT0 #3 LE-TIM0_OUT1 #2 PCNT0_S0IN #3 PCNT0_S1IN #2	US0_TX #3 US0_RX #2 US0_CLK #1 US0_CS #0 US0_CTS #31 US0_RTS #30 US1_TX #3 US1_RX #2 US1_CLK #1 US1_CS #0 US1_CTS #31 US1_RTS #30 LEU0_TX #3 LEU0_RX #2 I2C0_SDA #3 I2C0_SCL #2	PRS_CH6 #3 PRS_CH7 #2 PRS_CH8 #1 PRS_CH9 #0 ACMP0_O #3 ACMP1_O #3 LES_CH11 GPIO_EM4WU8

Table 6.7. ACMP1 Bus and Pin Mapping

Port	Bus	CH31	CH30	CH29	CH28	CH27	CH26	CH25	CH24	CH23	CH22	CH21	CH20	CH19	CH18	CH17	CH16	CH15	CH14	CH13	CH12	CH11	CH10	CH9	CH8	CH7	CH6	CH5	CH4	CH3	CH2	CH1	CH0
APORT0X	BUSACMP1X																									PJ15	PJ14						
APORT0Y	BUSACMP1Y																									PJ15	PJ14						
APORT1X	BUSAX		PF14		PF12		PF10		PF8		PF6		PF4		PF2		PF0						PC10		PC8		PC6		PC4		PC2		PC0
APORT1Y	BUSAY	PF15		PF13		PF11		PF9		PF7		PF5		PF3		PF1						PC11		PC9		PC7		PC5		PC3		PC1	
APORT2X	BUSBX	PF15		PF13		PF11		PF9		PF7		PF5		PF3		PF1						PC11		PC9		PC7		PC5		PC3		PC1	
APORT2Y	BUSBY		PF14		PF12		PF10		PF8		PF6		PF4		PF2		PF0						PC10		PC8		PC6		PC4		PC2		PC0
APORT3X	BUSCX		PB14		PB12		PB10		PB8		PB6							PA7	PA6		PA4		PA2		PA0		PD14		PD12		PD10		PD8
APORT3Y	BUSCY	PB15		PB13		PB11		PB9		PB7								PA7		PA5		PA3		PA1		PD15		PD13		PD11		PD9	
APORT4X	BUSDX	PB15		PB13		PB11		PB9		PB7								PA7		PA5		PA3		PA1		PD15		PD13		PD11		PD9	
APORT4Y	BUSDY		PB14		PB12		PB10		PB8		PB6							PA7	PA6		PA4		PA2		PA0		PD14		PD12		PD10		PD8

Port	Bus	CH31	CH30	CH29	CH28	CH27	CH26	CH25	CH24	CH23	CH22	CH21	CH20	CH19	CH18	CH17	CH16	CH15	CH14	CH13	CH12	CH11	CH10	CH9	CH8	CH7	CH6	CH5	CH4	CH3	CH2	CH1	CH0
VDAC0_OUT1 / OPA1_OUT																																	
APORT1Y	BUSAY	PF15		PF13		PF11		PF9		PF7		PF5		PF3		PF1						PC11		PC9		PC7		PC5		PC3		PC1	
APORT2Y	BUSBY		PF14		PF12		PF10		PF8		PF6		PF4		PF2		PF0						PC10		PC8		PC6		PC4		PC2		PC0
APORT3Y	BUSCY	PB15		PB13		PB11		PB9		PB7								PA7		PA5		PA3		PA1		PD15		PD13		PD11		PD9	
APORT4Y	BUSDY		PB14		PB12		PB10		PB8		PB6								PA6		PA4		PA2		PA0		PD14		PD12		PD10		PD8

8.2 QFN48 PCB Land Pattern

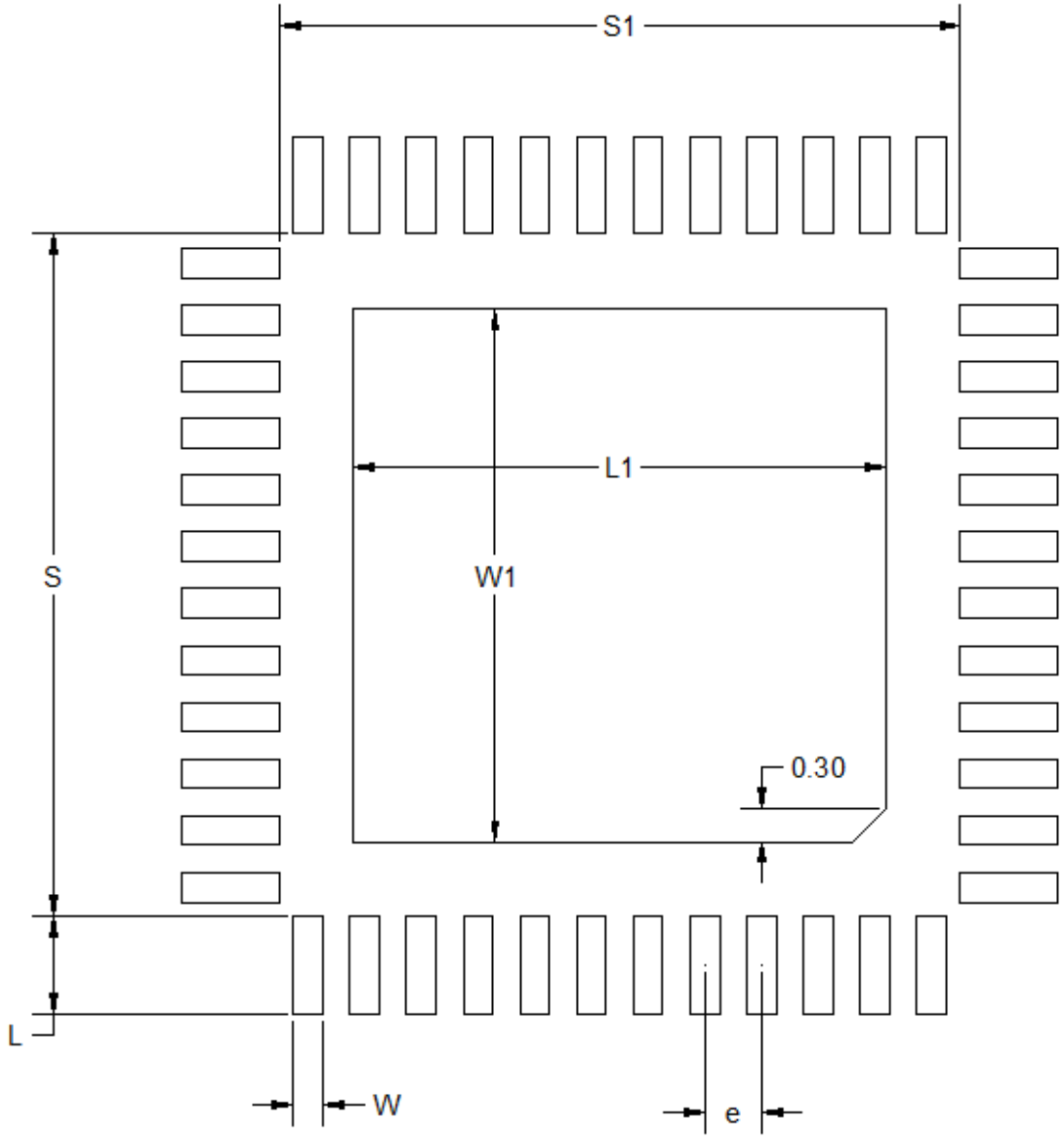

Figure 8.2. QFN48 PCB Land Pattern Drawing

8.3 QFN48 Package Marking

Figure 8.3. QFN48 Package Marking

The package marking consists of:

- PPPPPPPPPP – The part number designation.
- TTTTTT – A trace or manufacturing code. The first letter is the device revision.
- YY – The last 2 digits of the assembly year.
- WW – The 2-digit workweek when the device was assembled.

9. Revision History

9.1 Revision 0.5

2017-02-10

- Updated Feature List and Front Page with latest characterization numbers.
- List of OPNs in Ordering Table consolidated.
- Electrical Characteristics Table Changes
  - All specification tables updated with latest characterization data and production test limits.
  - Split HFRCO/AUXHFRCO table into separate tables for HFRCO and AUXHFRCO.
  - OPAMP, CSEN, and VDAC specification line items updated to match test conditions.
  - Added tables for Analog Port (APORT) and Pulse Counter (PCNT).
- Added Typical Performance Curves for supply current and DCDC parameters.
- Added APORT Connection Diagram.

9.2 Revision 0.2

December 9th, 2016

Initial release.

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